

Single Buffer

NL17SV16

The NL17SV16 is a single buffer in tiny footprint packages. The device is designed to operate for $V_{CC} = 0.9\text{ V}$ to 3.6 V .

Features

- Designed for 0.9 V to 3.6 V V_{CC} Operation
- 1.4 ns t_{PD} at 3.3 V (Typ)
- Inputs/Outputs Over-Voltage Tolerant up to 3.6 V
- I_{OFF} Supports Partial Power Down Protection
- Source/Sink 24 mA at 3.3 V
- Available in SOT-553 Package
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

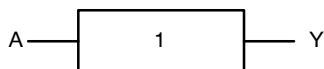
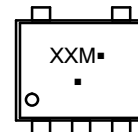


Figure 1. Logic Symbol

MARKING DIAGRAMS



**SOT-553, 5 LEAD
CASE 463B**



XX = Specific Device Code

M = Date Code*

▪ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 7 of this data sheet.

NL17SV16

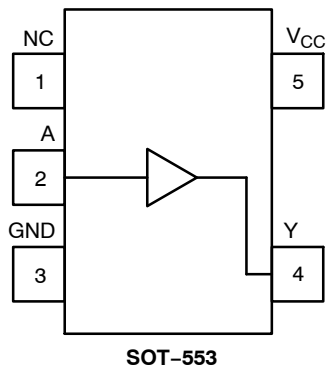


Figure 2. Pinout (Top View)

PIN ASSIGNMENT

Pin	SOT-553
1	NC
2	A
3	GND
4	Y
5	V _{CC}
6	–

FUNCTION TABLE

A Input	Y Output
L	L
H	H

MAXIMUM RATINGS

Symbol	Characteristics	Value	Unit
V_{CC}	DC Supply Voltage	-0.5 to +4.3	V
V_{IN}	DC Input Voltage	-0.5 to +4.3	V
V_{OUT}	DC Output Voltage Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode ($V_{CC} = 0$ V)	-0.5 to $V_{CC} + 0.5$ -0.5 to +4.3 -0.5 to +4.3	V
I_{IK}	DC Input Diode Current $V_{IN} < GND$	-50	mA
I_{OK}	DC Output Diode Current $V_{OUT} < GND$	-50	mA
I_{OUT}	DC Output Source/Sink Current	± 50	mA
I_{CC} or I_{GND}	DC Supply Current per Supply Pin or Ground Pin	± 50	mA
T_{STG}	Storage Temperature Range	-65 to +150	°C
T_L	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
T_J	Junction Temperature Under Bias	+150	°C
θ_{JA}	Thermal Resistance (Note 2) SOT-553	324	°C/W
P_D	Power Dissipation in Still Air SOT-553	386	mW
MSL	Moisture Sensitivity	Level 1	-
F_R	Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	-
V_{ESD}	ESD Withstand Voltage (Note 3) Human Body Model Charged Device Model	2000 1000	V
$I_{Latchup}$	Latchup Performance (Note 4)	± 100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Applicable to devices with outputs that may be tri-stated.
2. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow per JESD51-7.
3. HBM tested to EIA / JESD22-A114-A. CDM tested to JESD22-C101-A. JEDEC recommends that ESD qualification to EIA/JESD22-A115A (Machine Model) be discontinued.
4. Tested to EIA/JESD78 Class II.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V_{CC}	Positive DC Supply Voltage	0.9	3.6	V
V_{IN}	DC Input Voltage	0	3.6	V
V_{OUT}	DC Output Voltage Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode ($V_{CC} = 0$ V)	0 0 0	V_{CC} 3.6 3.6	
T_A	Operating Temperature Range	-55	+125	°C
t_r, t_f	Input Transition Rise and Fall Time	0	20	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Condition	V_{CC} (V)	$T_A = 25^\circ\text{C}$			$T_A = -55^\circ\text{C to } +125^\circ\text{C}$		Unit
				Min	Typ	Max	Min	Max	
V_{IH}	High-Level Input Voltage		0.9	–	0.5	–	–	–	V
			1.1 to 1.3	$0.65 \times V_{CC}$	–	–	$0.65 \times V_{CC}$	–	
			1.4 to 1.6	$0.65 \times V_{CC}$	–	–	$0.65 \times V_{CC}$	–	
			1.65 to 1.95	$0.65 \times V_{CC}$	–	–	$0.65 \times V_{CC}$	–	
			2.3 to < 2.7	1.6	–	–	1.6	–	
			2.7 to 3.6	2.0	–	–	2.0	–	
V_{IL}	Low-Level Input Voltage		0.9	–	0.5	–	–	–	V
			1.1 to 1.3	–	–	$0.35 \times V_{CC}$	–	$0.35 \times V_{CC}$	
			1.4 to 1.6	–	–	$0.35 \times V_{CC}$	–	$0.35 \times V_{CC}$	
			1.65 to 1.95	–	–	$0.35 \times V_{CC}$	–	$0.35 \times V_{CC}$	
			2.3 to < 2.7	–	–	0.7	–	0.7	
			2.7 to 3.6	–	–	0.8	–	0.8	
V_{OH}	High-Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$							V
		$I_{OH} = -100 \mu\text{A}$	0.9	–	$V_{CC} - 0.1$	–	–	–	
			1.1 to 1.3	$V_{CC} - 0.1$	–	–	$V_{CC} - 0.1$	–	
			1.4 to 1.6	$V_{CC} - 0.1$	–	–	$V_{CC} - 0.1$	–	
			1.65 to 1.95	$V_{CC} - 0.2$	–	–	$V_{CC} - 0.2$	–	
			2.3 to < 2.7	$V_{CC} - 0.2$	–	–	$V_{CC} - 0.2$	–	
			2.7 to 3.6	$V_{CC} - 0.2$	–	–	$V_{CC} - 0.2$	–	
		$I_{OH} = -2 \text{ mA}$	1.1 to 1.3	$0.75 \times V_{CC}$	–	–	$0.75 \times V_{CC}$	–	
		$I_{OH} = -4 \text{ mA}$	1.4 to 1.6	$0.75 \times V_{CC}$	–	–	$0.75 \times V_{CC}$	–	
		$I_{OH} = -6 \text{ mA}$	1.65 to 1.95	1.25	–	–	1.25	–	
			2.3 to 2.7	2.0	–	–	2.0	–	
		$I_{OH} = -12 \text{ mA}$	2.3 to 2.7	1.8	–	–	1.8	–	
			2.7 to 3.6	2.2	–	–	2.2	–	
		$I_{OH} = -18 \text{ mA}$	2.3 to 2.7	1.7	–	–	1.7	–	
			2.7 to 3.6	2.4	–	–	2.4	–	
		$I_{OH} = -24 \text{ mA}$	2.7 to 3.6	2.2	–	–	2.2	–	

DC ELECTRICAL CHARACTERISTICS (continued)

Symbol	Parameter	Condition	V _{CC} (V)	T _A = 25 °C			T _A = -55 °C to +125 °C		Unit
				Min	Typ	Max	Min	Max	
V _{OL}	Low-Level Output Voltage	V _{IN} = V _{IH} or V _{IL}							V
		I _{OL} = 100 µA	0.9	–	0.1	–	–	–	
			1.1 to 1.3	–	–	0.1	–	0.1	
			1.4 to 1.6	–	–	0.1	–	0.1	
			1.65 to 1.95	–	–	0.2	–	0.2	
			2.3 to < 2.7	–	–	0.2	–	0.2	
			2.7 to 3.6	–	–	0.2	–	0.2	
		I _{OL} = 2 mA	1.1 to 1.3	–	–	0.25 x V _{CC}	–	0.25 x V _{CC}	
		I _{OL} = 4 mA	1.4 to 1.6	–	–	0.25 x V _{CC}	–	0.25 x V _{CC}	
		I _{OL} = 6 mA	1.65 to 1.95	–	–	0.3	–	0.3	
			2.3 to 2.7	–	–	0.3	–	0.3	
		I _{OL} = 12 mA	2.3 to 2.7	–	–	0.4	–	0.4	
			2.7 to 3.6	–	–	0.4	–	0.4	
		I _{OL} = 18 mA	2.3 to 2.7	–	–	0.6	–	0.6	
			2.7 to 3.6	–	–	0.4	–	0.4	
		I _{OL} = 24 mA	2.7 to 3.6	–	–	0.55	–	0.55	
I _{IN}	Input Leakage Current	V _{IN} = 3.6 V or GND	0.9 to 3.6	–	–	±0.1	–	±0.9	µA
I _{OFF}	Power Off Leakage Current	V _{IN} = 3.6 V or V _{OUT} = 3.6 V	0	–	–	1.0	–	5.0	µA
I _{CC}	Quiescent Supply Current	V _{IN} = V _{CC} or GND	0.9 to 3.6	–	–	0.9	–	5.0	µA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Condition	V _{CC} (V)	T _A = 25 °C			T _A = -55 °C to +125 °C		Unit
				Min	Typ	Max	Min	Max	
t _{PLH} , t _{PHL}	Propagation Delay, A to Y (Figures 3 and 4)	R _L = 1 MΩ, C _L = 15 pF	0.9	–	18.49	–	–	–	ns
		R _L = 2 kΩ, C _L = 15 pF	1.1 to 1.3	–	5.4	13.0	–	16.9	
			1.4 to 1.6	–	3.2	6.1	–	7.0	
		R _L = 500 Ω, C _L = 30 pF	1.65 to 1.95	–	2.3	5.2	–	6.2	
			2.3 to 2.7	–	1.7	3.7	–	4.4	
			2.7 to 3.6	–	1.4	3.3	–	3.8	

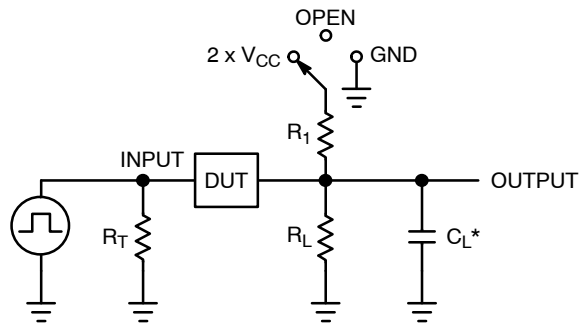
CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Test Condition	Typical (T _A = 25 °C)	Unit
C _{IN}	Input Capacitance	V _{CC} = 0 V	2.0	pF
C _{OUT}	Output Capacitance	V _{CC} = 0 V	4.5	pF
C _{PD}	Power Dissipation Capacitance (Note 5)	10 MHz, V _{CC} = 0.9 to 3.6 V, V _{IN} = 0 V or V _{CC}	20	pF

5. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no-load dynamic power consumption: P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.



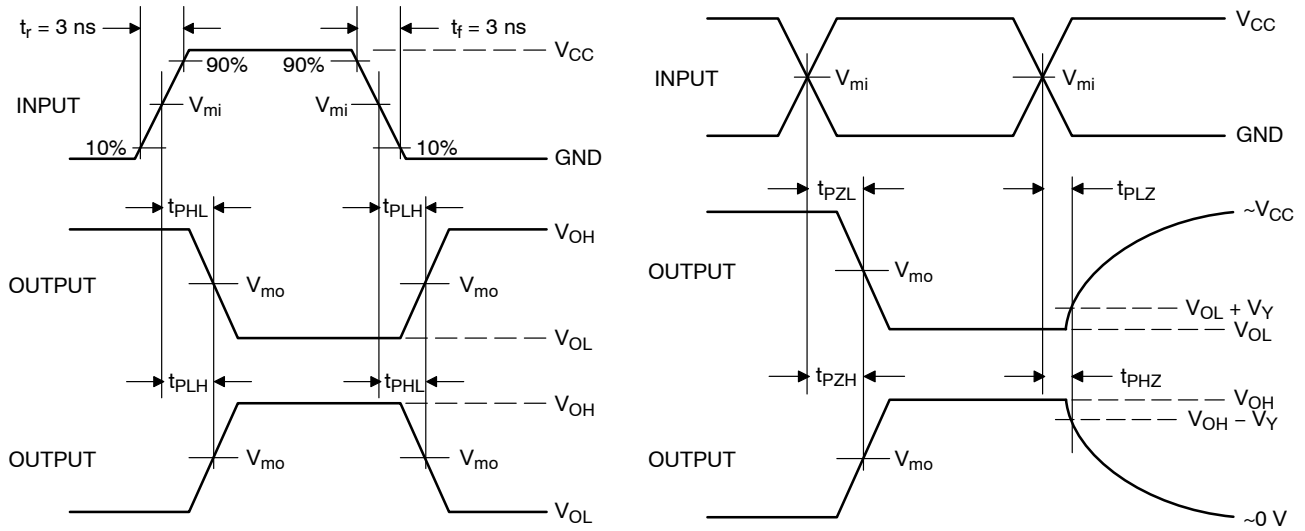
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C_L includes probe and jig capacitance
 R_T is Z_{OUT} of pulse generator (typically 50 Ω)
 $f = 1$ MHz

Test	Switch Position
t_{PLH} / t_{PHL}	Open
t_{PLZ} / t_{PZL}	$2 \times V_{CC}$
t_{PHZ} / t_{PZH}	GND

Figure 3. Test Circuit



V_{CC}, V	V_{mi}, V	V_{mo}, V		V_Y, V
		t_{PLH}, t_{PHL}	$t_{PZL}, t_{PLZ}, t_{PZH}, t_{PHZ}$	
0.9	$V_{CC} / 2$	$V_{CC} / 2$	$V_{CC} / 2$	0.1
1.1 to 1.3	$V_{CC} / 2$	$V_{CC} / 2$	$V_{CC} / 2$	0.1
1.4 to 1.6	$V_{CC} / 2$	$V_{CC} / 2$	$V_{CC} / 2$	0.1
1.65 to 1.95	$V_{CC} / 2$	$V_{CC} / 2$	$V_{CC} / 2$	0.15
2.3 to 2.7	$V_{CC} / 2$	$V_{CC} / 2$	$V_{CC} / 2$	0.15
3.0 to 3.6	1.5	1.5	1.5	0.3

Figure 4. Switching Waveforms

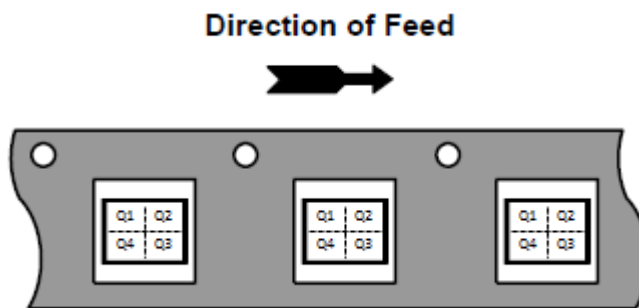
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ORDERING INFORMATION

Device	Package	Marking	Pin 1 Orientation (See below)	Shipping [†]
NL17SV16XV5T2G	SOT-553	UN	Q4	4000 / Tape & Reel

[†] For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

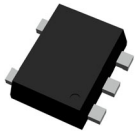
PIN 1 ORIENTATION IN TAPE AND REEL



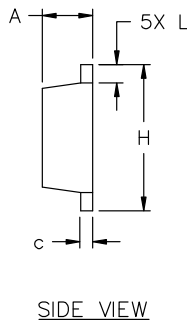
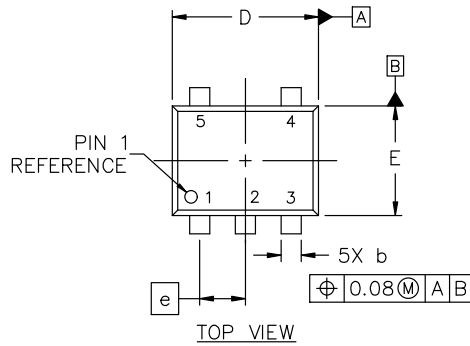
REVISION HISTORY

Revision	Description of Changes	Date
9	Removed five package ordering options and OPNs	1/15/2026

*Please note that this document has been previously updated prior to the inclusion of this revision history table and that the changes tracked only reflect what has occurred on the noted approval dates.


SOT-553-5 1.60x1.20x0.55, 0.50P
CASE 463B
ISSUE D

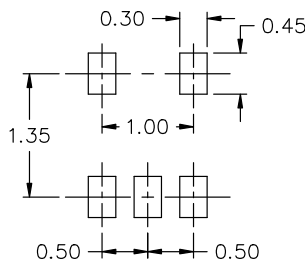
DATE 21 FEB 2024



NOTES:

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
2. ALL DIMENSION ARE IN MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.50	0.55	0.60
b	0.17	0.22	0.27
c	0.08	0.13	0.18
D	1.55	1.60	1.65
E	1.15	1.20	1.25
e	0.50 BSC		
H	1.55	1.60	1.65
L	0.10	0.20	0.30



RECOMMENDED MOUNTING FOOTPRINT*

- * FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERM/D.

GENERIC MARKING DIAGRAM*


XX = Specific Device Code
M = Date Code
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLE 1:
PIN 1. BASE
2. EMITTER
3. BASE
4. COLLECTOR
5. COLLECTOR

STYLE 2:
PIN 1. CATHODE
2. COMMON ANODE
3. CATHODE 2
4. CATHODE 3
5. CATHODE 4

STYLE 3:
PIN 1. ANODE 1
2. N/C
3. ANODE 2
4. CATHODE 2
5. CATHODE 1

STYLE 4:
PIN 1. SOURCE 1
2. DRAIN 1/2
3. SOURCE 1
4. GATE 1
5. GATE 2

STYLE 5:
PIN 1. ANODE
2. EMITTER
3. BASE
4. COLLECTOR
5. CATHODE

STYLE 6:
PIN 1. EMITTER 2
2. BASE 2
3. EMITTER 1
4. COLLECTOR 1
5. COLLECTOR 2/BASE 1

STYLE 7:
PIN 1. BASE
2. EMITTER
3. BASE
4. COLLECTOR
5. COLLECTOR

STYLE 8:
PIN 1. CATHODE
2. COLLECTOR
3. N/C
4. BASE
5. EMITTER

STYLE 9:
PIN 1. ANODE
2. CATHODE
3. ANODE
4. ANODE
5. ANODE

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